

Final Product/Process Change Notification Document #:FPCN23597XC1

Issue Date:08 Dec 2021

Title of Change:	Update to FPCN23597XC – To correct the title to "Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - MC1413 and ULN2003 families."		
Proposed First Ship date:	10 Feb 2022 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or Jan.Gryzbon@onsemi.com		
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local onsemi Sales Office or < PCN.samples@onsemi.com >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onse	Contact your local onsemi Sales Office or <u>Tomas.Vajter@onsemi.com</u>	
Type of Notification:	days prior to implemer onsemi will consider th	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	The affected products	The affected products will be identified with date code	
Change Category:	Wafer Fab Change	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Process	Manufacturing Process Change	
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic		None	

Description and Purpose:

This update notification is being issued to clarify and correct the Title from Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - MC1413 and UNL2003 families to "Conversion of select onsemi, Czech Republic (Roznov) wafer fab technologies from 150mm to 200mm wafer diameter - MC1413 and ULN2003 families.

Reliability Data Summary:

QV DEVICE NAME: NCV1413BDR2G

RMS# 68977 DACKAGE: SOIC16

Test	Specification	Condition	Interval	Results
HTOL	JA108	Ta= 125°C	2016 hrs	0/240
PC	JA112 JA113	SMD only, Test @ 0 & EP		0/372
SAT		Test pre- and post- PC		pass
ELFR	JA018	TA = 125°C for 48 hrs	48hrs	0/2400
TC	JA104	Test @ R	1000сус	0/270
BS	AEC-Q100-001	Cpk 1.33, 30 bonds from 5units		pass
BPS	M883 Method 2011	3gm Pull Force Min After TC		pass
ESD HBM	AEC-Q100-002	c = 0, Test @ R	2kV	0/3
ESD CDM	AEC-Q100-011	c = 0, Test @ R	1.5kV	0/3
ED	ON Data Sheet	Cpk > 1.67 Test @ R, H, C	Cpk>1.67	pass

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LU AEC-Q100-004	Test @ EP; Test & Stress @ R	LU+>100mA LU->100mA	0/6
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Electrical Characteristics Summary:

Electrical characteristics are not impacted. All Data Sheet specifications remain the same.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
ULQ2003ADR2G	ULN2003ADR2G	
MC1413BDR2G	ULN2003ADR2G	
MC1413DR2G	ULN2003ADR2G	
ULN2003ADR2G	ULN2003ADR2G	

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